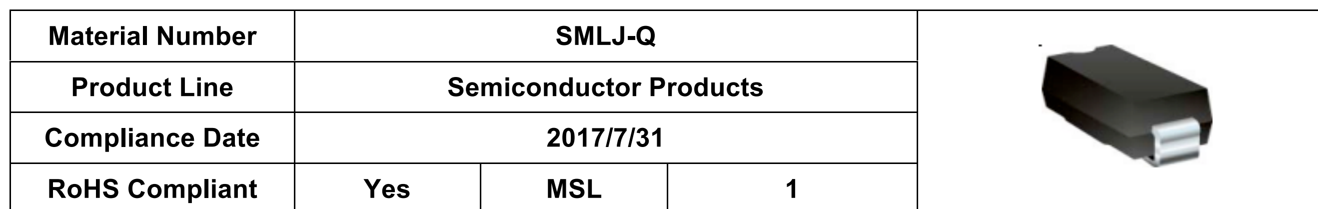
MATERIAL DECLARATION SHEET



Material Number	SMLJ-Q		
Product Line	Semiconductor Products		
Compliance Date	2017/7/31		
RoHS Compliant	Yes	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silicon	0.004829	Silicon (Si)	7440-21-3	60.1800%	1.221%	2.028%
				Phosphorous(P)	7723-14-0	0.0100%	0.0002%	
				Boron(B)	7440-42-8	0.0100%	0.0002%	
				Nickel (Ni)	7440-02-0	14.8000%	0.300%	
				PbO	1317-36-8	12.5000%	0.254%	
				SiO_2	7631-86-9	10.0000%	0.203%	
				Al_2O_3	1344-28-1	2.5000%	0.0507%	
2	Die attach (Solder)	solder paste	0.009170	Tin (Sn)	7440-31-5	5.000%	0.193%	3.851%
				Lead (Pb)	7439-92-1	92.500%	3.563%	
				(Ag)	7440-22-4	2.500%	0.096%	
3	Lead frame	Copper	0.110667	Copper (Cu)	7440-50-8	99.800%	46.388%	46.481%
				Iron (Fe)	7439-89-6	0.150%	0.070%	
				P	7723-14-0	0.050%	0.023%	
4	Molding compound	Epoxy material	0.112150	Silica (SiO_2)	14808-60-7	76.000%	35.799%	47.104%
				Epoxy resin	25928-94-3	9.000%	4.239%	
				Phenolic resin-A,-B	9003-35-4	8.000%	3.768%	
				Hydroxide metal	-	6.000%	2.826%	
				Carbon	1333-86-4	1.000%	0.471%	
5	Plating	Matte-Tin	0.001275	Tin (Sn)	7440-31-5	100.000%	0.536%	0.536%
		Total weight	0.238091g					

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society

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BOURNS®

This Document was updated on: 2017/7/31

Important remarks:

1. **It is the responsibility of the user to verify they are accessing the latest version.**
2. **7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)**
3. **7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.**

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